

Amendments to the Claims

1. *(Currently Amended)* An electronic device comprising a free-standing thin film (30), the thin film (30)-comprising an alloy of aluminum and at least magnesium.

2. *(Original)* An electronic device as claimed in claim 1, comprising an alloy of aluminum, magnesium and at least one further material.

3. *(Original)* An electronic device as claimed in Claim 2, wherein said at least one further material comprises one or more of copper, manganese, silicon, nickel, chromium, and lithium.

4. *(Currently Amended)* An electronic device as claimed in Claim 1-2 or 3claim 1, wherein the Mg content is between 0.1 and 10 atomic weight per cent.

5. *(Original)* An electronic device as claimed in Claim 3, wherein said one further material comprises copper in an amount between 0.1 and 8 atomic weight per cent.

6. *(Currently Amended)* An electronic device as claimed in Claim 3 or 5claim 3, wherein the sum of the contents of magnesium, copper and manganese is between 2.5 and 10 atomic weight per cent.

7. *(Currently Amended)* An electronic device as claimed in Claim 3 or 6claim 3, wherein the alloy is chosen from the group of $A1_vMg_wCu_xMn_y$, $A1_vMg_wMn_y$, $A1_vMg_wCu_xSi_zNi_{z2}$, $A1_vMg_wCu_x$, $A1_vMg_wCu_xSi_{z1}$, $A1_vMg_wCu_xZn_{z3}Cr_{z4}$, $A1_vMg_wCu_xLi_{z5}$, with $80 \leq v \leq 99.8$; and $0.1 \leq w \leq 8.0$, $0.1 \leq x \leq 8.0$, $0.1 \leq y \leq 4.0$ and $z1, z2, z3, z4, z5$ each smaller than 20, and preferably smaller than 5.

8. *(Currently Amended)* A method of manufacturing an electronic device comprising a free-standing thin film (30), the method comprising the steps of:
- providing a mechanical layer of material (42) on a sacrificial release layer (16,17);

- structuring said mechanical layer {12} to define the film {30}; and
- removing said release layer {16, 17} to render said film {30} free-standing, characterized in that said top layer comprises an alloy of aluminum and at least magnesium.

9. *(Currently Amended)*

A method according to claim 8, wherein said release layer {16, 17} is patterned prior to provision of said mechanical layer {12} thereon.